INTEGRATED CIRCUIT DEVICE AND PROCESS FOR ITS MANUFACTURE

ABSTRACT

The invention relates to an integrated circuit device comprising (i) a substrate (2); (ii) metallic circuit lines (4) positioned on the substrate (2) and (iii) a dielectric material (6) positioned on the circuit lines (4). The dielectric material (6) comprises the reaction product of an organic polysilica and polyamic ester preferably terminated with an alkoxysilyl alkyl group.

Fig. 1